Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-8. (Canceled)

9. (Original) A method of fabricating a lead frame for a semiconductor device package, the method comprising:

providing a first layer;

patterning a first mask over the first layer to reveal first exposed regions;

electroplating a first metal over the first layer in the first exposed regions;

patterning a second mask over the first mask to reveal second exposed regions;

electroplating a second metal over the first mask in the second exposed regions;

removing the first and second masks; and

encapsulating at least a portion of the first metal and the second metal within dielectric material.

10. (Original) The method of claim 9 wherein the first metal and the second metal are the same.

11. (Original) The method of claim 9 wherein:

patterning the first mask comprises patterning a negative photoresist mask; and

patterning the second mask comprises patterning a negative photoresist mask.

12. (Original) The method of claim 11 wherein removing the negative and positive photoresist masks defines a lead frame comprising a diepad portion and a pin portion, the method further comprising:

encapsulating the lead frame within a plastic package body; and

separating the first metal from the first layer, wherein the first exposed regions correspond to a pin portion exposed on a surface of the package body.

13. (Original) The method of claim 12 wherein the lead frame is encapsulated within a cell of a mold, such that individual packages are singulated upon separation of the first metal from the first layer.

14. (Original) The method of claim 12 further comprising:

forming an etch stop layer over the first metal prior to forming the second metal;

etching a portion of the first metal revealed by separation from the first layer to form a cavity; and

introducing additional dielectric material within the cavity.

15. (Original) The method of claim 14 wherein forming the etch stop layer comprises electroplating a metal different from the first and second metals within the first exposed regions.

16 -23 (Canceled)

24. (Original) A method of fabricating a metal lead frame, the method comprising:

patterning a negative photoresist mask over a substrate;

electroplating raised portions of a copper lead frame within regions exposed by the negative photoresist mask;

patterning a positive photoresist mask over the negative photoresist mask and the raised copper portions;

electroplating diepad and pin portions of the copper lead frame within regions exposed by the positive photoresist mask;

removing the negative and positive photoresist masks;

attaching a die to the diepad;

encapsulating the die and lead frame within plastic; and

separating the raised copper portions and the plastic from the substrate.

25. (Original) The method of claim 24 further comprising singulating the encapsulated die and lead frame from adjacent packages by sawing.

26. (Original) The method of claim 25 wherein:

the die and lead frame are encapsulated within a cell of a surrounding mold; and

separation of the raised copper portions and the plastic from the substrate is accomplished by chemical etching, resulting in singulation of the encapsulated die and lead frame from adjacent packages.

27-28. (Canceled)